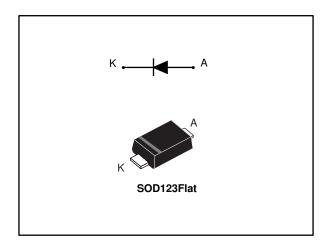


STPS2H100ZFY

Automotive high voltage power Schottky rectifier

Datasheet - production data



Features



- AEC-Q101 qualified
- High junction temperature capability
- Low leakage current
- Negligible switching losses
- Avalanche capability specified
- ECOPACK®2 compliant component
- PPAP capable

Description

Single chip Schottky rectifiers suited to automotive applications, such as lighting, diesel injection, or engine control unit.

Packaged in SOD123Flat, this device is especially intended for surface mounting and used in high frequency converters, free wheeling and reverse polarity protection in automotive applications.

Table 1: Device summary

| Symbol | Value |
|-----------------------|--------|
| l _{F(AV)} | 2 A |
| V_{RRM} | 100 V |
| V _F (typ.) | 0.65 V |
| T _j (max.) | 175 °C |

Characteristics STPS2H100ZFY

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

| Symbol | Parameter | Value | Unit | |
|--------------------|---|-------------|------|---|
| V_{RRM} | Repetitive peak reverse voltage $T_j = -40 \text{ °C to } +175 \text{ °C}$ | | 100 | V |
| I _{F(AV)} | Average forward current δ = 0.5, square wave $T_L = 140 ^{\circ}\text{C}$ | | 2 | Α |
| I _{FSM} | Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$ | | 50 | Α |
| P _{ARM} | Repetitive peak avalanche power $t_p = 10 \mu s$, $T_j = 125 °C$ | | 105 | W |
| T _{stg} | Storage temperature range | -65 to +175 | °C | |
| Tj | Operating junction temperature range ⁽¹⁾ | -40 to +175 | J | |

Notes:

Table 3: Thermal parameters

| Symbol | Parameter | Max. value | Unit |
|----------------------|------------------|------------|------|
| R _{th(j-l)} | Junction to lead | 20 | °C/W |

Table 4: Static electrical characteristics

| | Symbol | Parameter | Test con | ditions | Min. | Тур. | Max. | Unit |
|--|-------------------------------|---|-------------------------|---------------------------------|------|------|------|------|
| | L (f) | Payaraa laakaga aurrant | T _j = 25 °C | $V_{\text{R}} = V_{\text{RRM}}$ | 1 | | 1 | μΑ |
| | IR ^(*) | I _R ⁽¹⁾ Reverse leakage current | T _j = 125 °C | | ı | 0.2 | 0.5 | mA |
| | V _F ⁽²⁾ | Forward voltage drop | T _j = 25 °C | I _F = 2 A | - | | 0.86 | V |
| | | | T _j = 125 °C | | - | 0.65 | 0.70 | |
| | | | T _j = 25 °C | F = 4 A | - | | 0.96 | |
| | | | T _j = 125 °C | | - | 0.75 | 0.83 | |

Notes:

 $^{(1)}$ Pulse test: t_p = 5 ms, δ < 2%

 $^{(2)}$ Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.57 \times I_{F(AV)} + 0.065 \times I_{F^{2}(RMS)}$

For more information, please refer to the following application notes related to the power losses.

- AN604 (Calculation of conduction losses in a power rectifier)
- AN4021 (Calculation of reverse losses in a power diode)

 $^{^{(1)}(}dP_{tot}/dT_j) < (1/R_{th(j\text{-}a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$

STPS2H100ZFY Characteristics

1.1 Characteristics (curves)

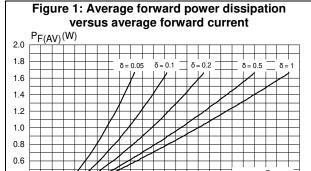
0.4

0.2

0.0

0.0

0.001



1.0

 $I_{F(AV)}(A)$

100

1000

 $\delta_i = tp/T$

1.2 1.4 1.6 1.8 2.0 2.2 2.4

Figure 2: Average forward current versus ambient temperature ($\delta = 0.5$) $I_{F(AV)}(A)$ $R_{th(i-a)} = R_{th(i-1)}$ 6 5 3 2 T_{amb}(°C) $\delta = tp/T$ 0 0 25 50 75 100 175 125

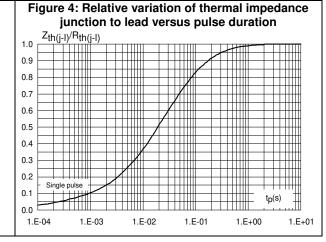
Figure 3: Normalized avalanche power derating versus pulse duration (T_j = 125 °C)

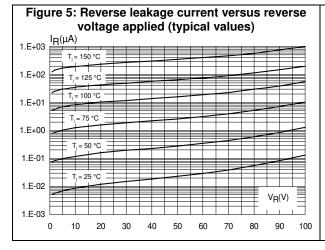
PARM(10 µS)

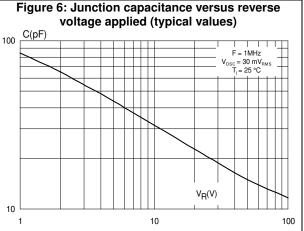
0.1

0.1

10







Characteristics STPS2H100ZFY

Figure 7: Forward voltage drop versus forward current (typical values) IF(A)10.00 T_i = 75 °C 1.00 0.10 0.01 0.0 0.1 0.2 0.3 0.6 0.7 0.9 1.0 1.1

Figure 8: Thermal resistance junction to ambient versus copper surface under each lead (typical values) R_{th(j-a)}(°C/W) 250 200 150 100 Epoxy printed board FR4, e_{Cu} = 35 μm 50 S_{Cu} (cm²) 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 5.0

STPS2H100ZFY Package information

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

2.1 SOD123Flat package information

Figure 9: SOD123Flat package outline

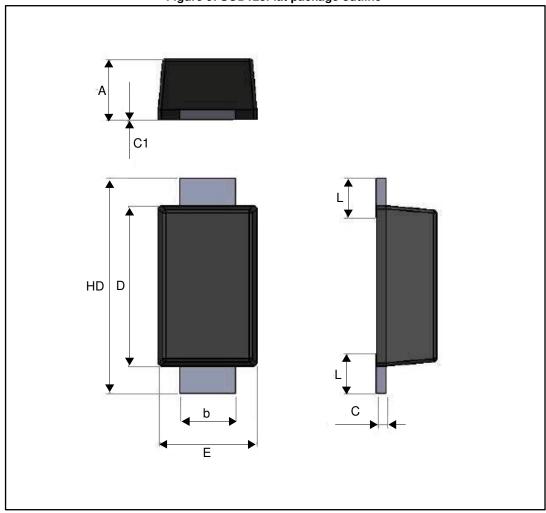
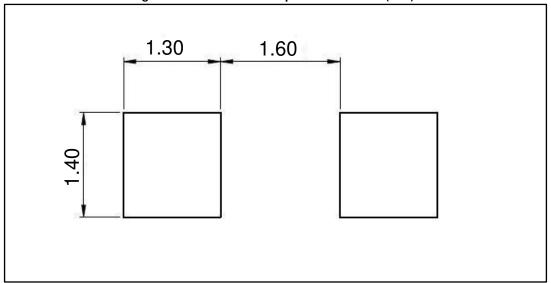


Table 5: SOD123Flat package mechanical data

| | Dimensions | | | | |
|------|-------------|------|------|--|--|
| Ref. | Millimeters | | | | |
| | Min. | Тур. | Max. | | |
| Α | 0.86 | 0.98 | 1.10 | | |
| b | 0.80 | 0.90 | 1.00 | | |
| С | 0.08 | 0.15 | 0.25 | | |
| c1 | 0.00 | | 0.10 | | |
| D | 2.50 | 2.60 | 2.70 | | |
| Е | 1.50 | 1.60 | 1.80 | | |
| HD | 3.30 | 3.50 | 3.70 | | |
| L | 0.45 | 0.65 | 0.85 | | |

Figure 10: SOD123Flat footprint dimensions (mm)



STPS2H100ZFY Ordering information

3 Ordering information

Table 6: Ordering information

| Order code | Marking | Package | Weight | Base qty. | Delivery mode |
|--------------|---------|------------|---------|-----------|---------------|
| STPS2H100ZFY | 2Y1 | SOD123Flat | 12.5 mg | 3000 | Tape and reel |

4 Revision history

Table 7: Document revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 20-Oct-2016 | 1 | Initial release. |

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